



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 60601  
Application ID: 10763859  
Title of Invention: SEMICONDUCTOR PACKAGE  
HAVING REDUCED THICKNESS  
First Named Inventor: TAE LEE  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2004-01-23  
Effective Receipt Date: 2004-05-07  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 8528  
Attorney Docket Number: AMKOR053G




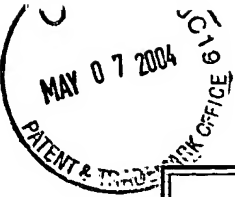
Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: da3188c6e20c3c6fb06a652e809c4b439fd81a81

**TRANSMITTAL**

Electronic Version v1.1  
Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS</b>									
<p>Application Number: 10/763859 </p> <p>Date: 2004-01-23</p> <p>First Named Applicant: TAE HEON LEE</p> <p>Confirmation Number: 8528</p> <p>Attorney Docket Number: AMKOR053G</p>										
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign..</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign..	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign..	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
<b>Comments</b>										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

SEMICONDUCTOR PACKAGE HAVING REDUCED  
THICKNESS

Application Number: 10/763859



Confirmation Number: 8528

First Named Applicant: TAE LEE

Attorney Docket Number: AMKOR053G

Art Unit: 2811

Search string: ( 5216278 or 5218231 or 5221642 or 5250841  
or 5252853 or 5258094 or 5266834 or 5273938  
or 5277972 or 5278446 or 5279029 or 5281849  
or 5294897 or 5327008 or 5332864 or 5335771  
or 5336931 or 5343076 or 5358905 or 5365106  
or 5381042 or 5391439 or 5406124 or 5410180  
or 5414299 or 5417905 or 5424576 or 5428248  
or 5435057 or 5444301 or 5452511 or 5454905  
or 5474958 or 5484274 or 5493151 or 5508556  
or 5517056 or 5521429 or 5528076 or 5534467  
or 5539251 or 5543657 or 5544412 or 5545923  
or 5581122 or 5592019 or 5592025 or 5594274  
or 5595934 or 5604376 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5216278	1993-06-01	Lin et al.			
	2	5218231	1993-06-08	Kudo			
	3	5221642	1993-06-22	Burns			
	4	5250841	1993-10-05	Sloan et al.			
	5	5252853	1993-10-12	Michii			
	6	5258094	1993-11-02	Furui et al.			
	7	5266834	1993-11-30	Nishi et al.			
	8	5273938	1993-12-28	Lin et al.			
	9	5277972	1994-01-11	Sakumoto et al.			

	10	5278446	1994-01-11	Nagaraj et al.
	11	5279029	1994-01-18	Burns
	12	5281849	1994-01-25	Singh Deo et al.
	13	5294897	1994-03-15	Notani et al.
	14	5327008	1994-06-05	Djennas et al.
	15	5332864	1994-07-26	Liang et al.
	16	5335771	1994-08-09	Murphy
	17	5336931	1994-08-09	Juskey et al.
	18	5343076	1994-08-30	Katayama et al.
	19	5358905	1994-10-25	Chiu
	20	5365106	1994-11-15	Watanabe
	21	5381042	1995-01-10	Lerner et al.
	22	5391439	1995-02-21	Tomita et al.
	23	5406124	1995-04-11	Morita et al.
	24	5410180	1995-04-25	Fujii et al.
	25	5414299	1995-05-09	Wang et al.
	26	5417905	1995-05-23	LeMaire et al.
	27	5424576	1995-06-13	Djennas et al.
	28	5428248	1995-06-27	Cha
	29	5435057	1995-07-25	Bindra et al.
	30	5444301	1995-08-22	Song et al.
	31	5452511	1995-09-26	Chang
	32	5454905	1995-10-03	Fogelson
	33	5474958	1995-12-12	Djennas et al.
	34	5484274	1996-01-16	Neu
	35	5493151	1996-02-20	Asada et al.
	36	5508556	1996-04-16	Lin
	37	5517056	1996-05-14	Bigler et al.
	38	5521429	1996-05-28	Aono et al.
	39	5528076	1996-06-18	Pavio
	40	5534467	1996-07-09	Rostoker
	41	5539251	1996-07-23	Iverson et al.
	42	5543657	1996-08-06	Diffenderfer et al.
	43	5544412	1996-08-13	Romero et al.
	44	5545923	1996-08-13	Barber
	45	5581122	1996-12-03	Chao et al.

	46	5592019	1997-01-07	Ueda et al.
	47	5592025	1997-01-07	Clark et al.
	48	5594274	1997-01-14	Suetaki
	49	5595934	1997-01-21	Kim
	50	5604376	1997-02-18	Hamburgen et al.

Signature

Examiner Name	Date